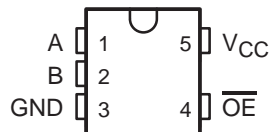


SN74CBTD1G384 SINGLE FET BUS SWITCH WITH LEVEL SHIFTING

SCDS066C – JULY 1998 – REVISED MAY 2000

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Control Input Levels
- Package Options Include Plastic Small-Outline Transistor (DBV, DCK) Packages

DBV OR DCK PACKAGE
(TOP VIEW)



description

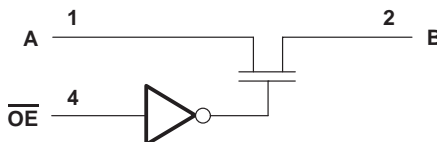
The SN74CBTD1G384 features a single high-speed line switch. The switch is disabled when the output-enable (\overline{OE}) input is high. A diode to V_{CC} is integrated on the chip to allow for level shifting between 5-V inputs and 3.3-V outputs.

The SN74CBTD1G384 is characterized for operation from -40°C to 85°C .

FUNCTION TABLE

INPUT \overline{OE}	FUNCTION
L	A port = B port
H	Disconnect

logic diagram (positive logic)



PRODUCT PREVIEW



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.

**TEXAS
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SN74CBTD1G384

SINGLE FET BUS SWITCH

WITH LEVEL SHIFTING

SCDS066C – JULY 1998 – REVISED MAY 2000

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DBV package	206°C/W
DCK package	252°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4.5	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [‡]	MAX	UNIT
V _{IK}		V _{CC} = 4.5 V, I _I = −18 mA				−1.2	V
V _{OH}		See Figure 2					
I _I		V _{CC} = 5.5 V, V _I = 5.5 V or GND				±1	μA
I _{CC}		V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND				1	μA
C _i	Control input	V _I = 3 V or 0					pF
C _{io} (OFF)		V _O = 3 V or 0, \overline{OE} = V _{CC}					pF
r _{on} [§]		V _{CC} = 4.5 V	V _I = 0	I _I = 64 mA			Ω
				I _I = 30 mA			
			V _I = 2.4 V, I _I = 15 mA				

[‡] All typical values are at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$.

[§] Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

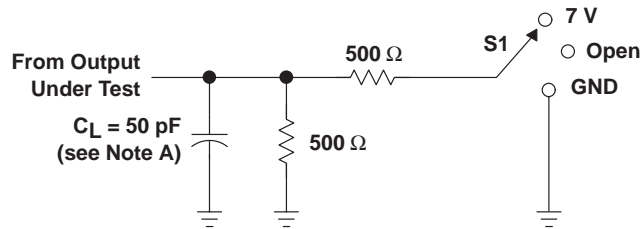
switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
t_{pd}^{\parallel}	A or B	B or A			ns
t_{en}	\overline{OE}	A or B			ns
t_{dis}	\overline{OE}	A or B			ns

^{||} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

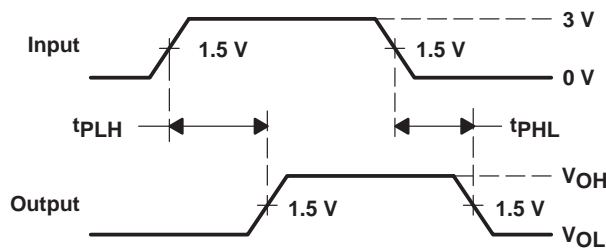


PARAMETER MEASUREMENT INFORMATION

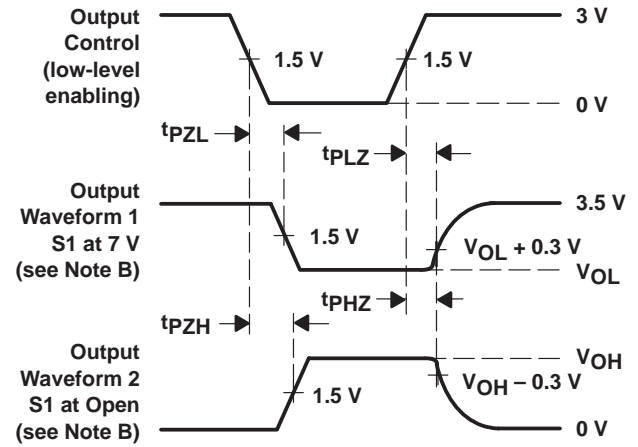


LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The output is measured with one input transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

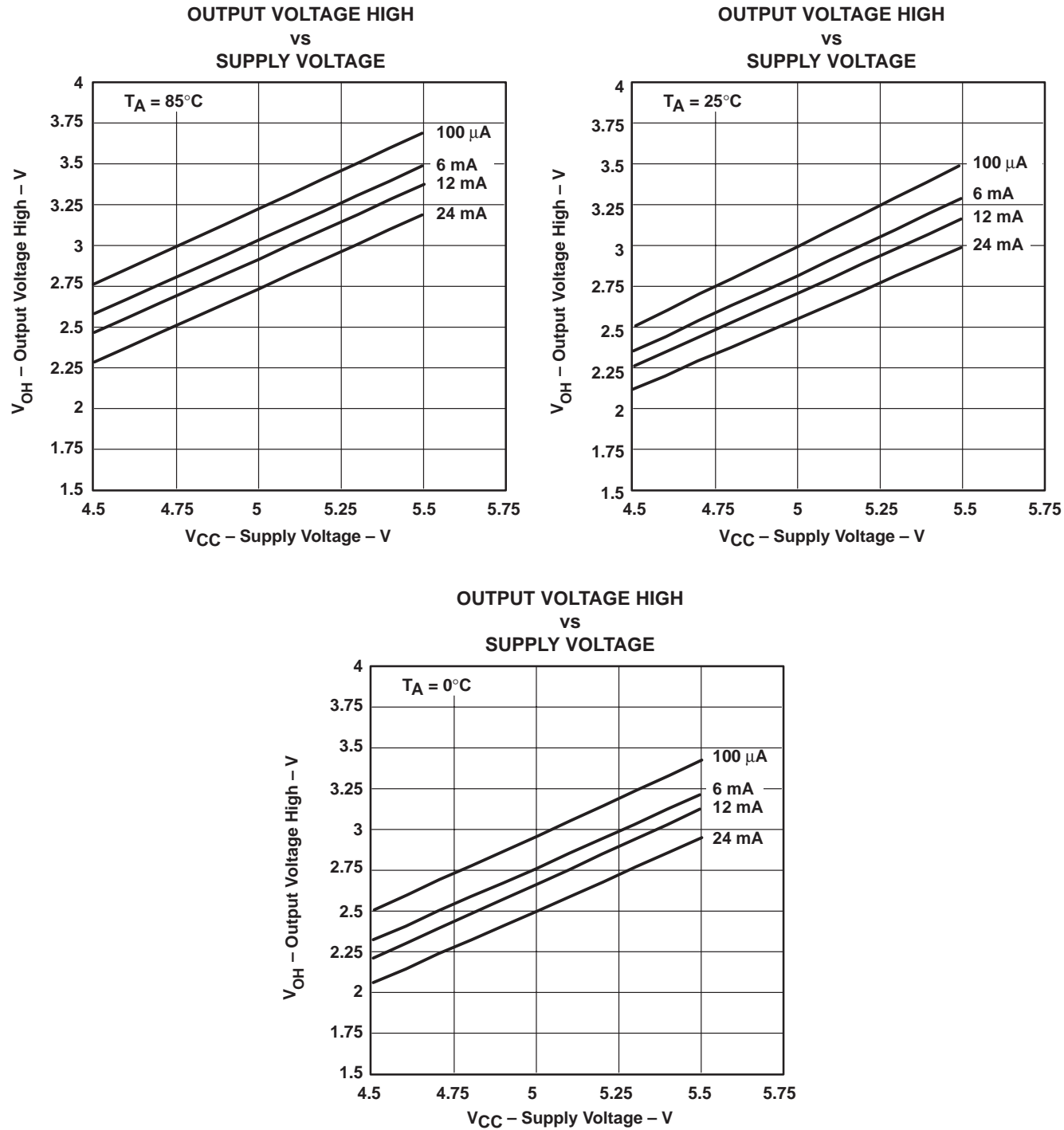


Figure 2. V_{OH} Values

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